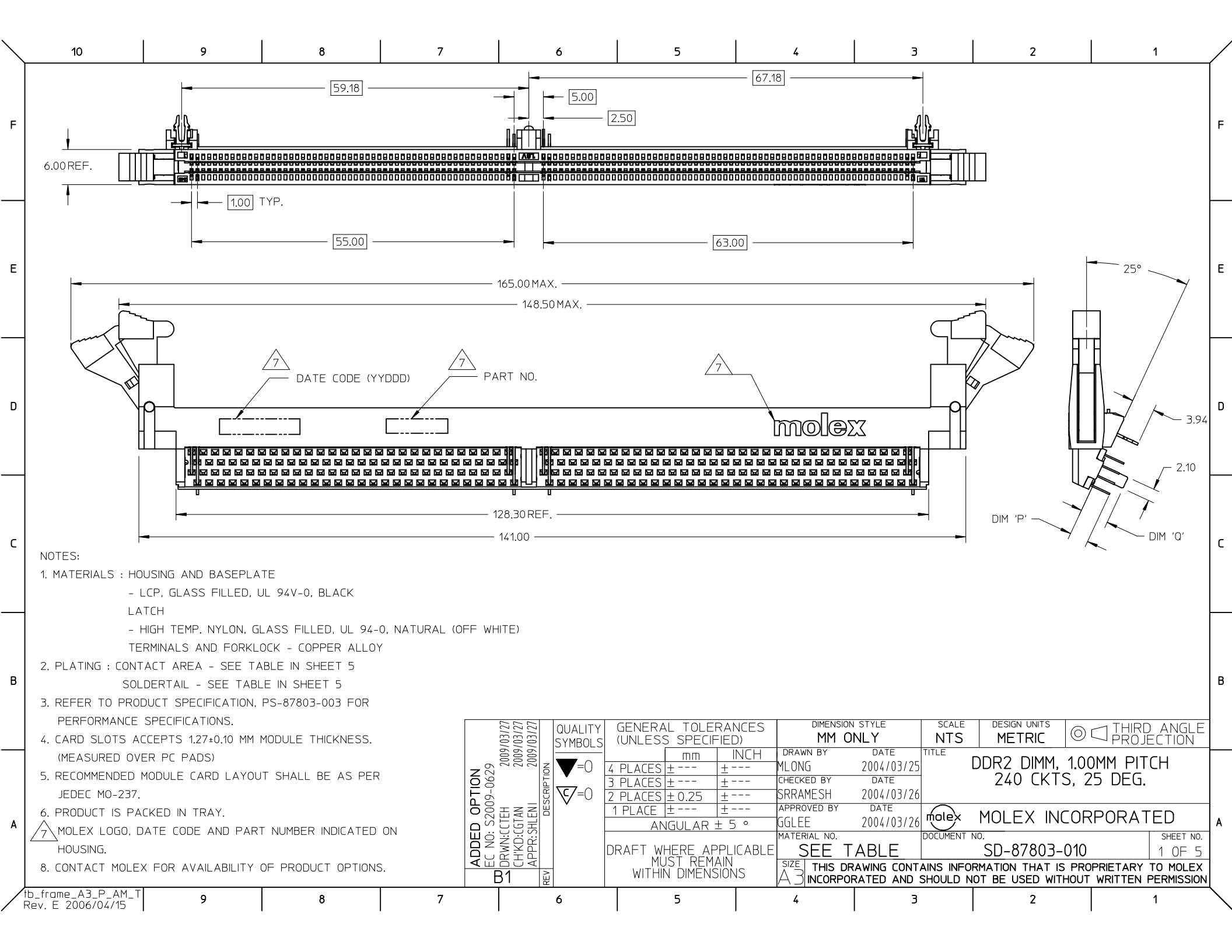




NOTES:

1. MATERIALS : HOUSING AND BASEPLATE
- LCP, GLASS FILLED, UL 94V-0, BLACK
LATCH
- HIGH TEMP. NYLON, GLASS FILLED, UL 94-0, NATURAL (OFF WHITE)
TERMINALS AND FORKLOCK - COPPER ALLOY
2. PLATING : CONTACT AREA - SEE TABLE IN SHEET 5
SOLDERTAIL - SEE TABLE IN SHEET 5
3. REFER TO PRODUCT SPECIFICATION, PS-87803-003 FOR PERFORMANCE SPECIFICATIONS.
4. CARD SLOTS ACCEPTS 1.27±0.10 MM MODULE THICKNESS. (MEASURED OVER PC PADS)
5. RECOMMENDED MODULE CARD LAYOUT SHALL BE AS PER JEDEC MO-237.
6. PRODUCT IS PACKED IN TRAY.
7. MOLEX LOGO, DATE CODE AND PART NUMBER INDICATED ON HOUSING.
8. CONTACT MOLEX FOR AVAILABILITY OF PRODUCT OPTIONS.

ADDED OPTION EC NO: S2009-0629 2009/03/27 DRWN:CCTEH CHKD:CGTAN 2009/03/27 APPR:SHLENI 2009/03/27	DESCRIPTION	QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION			
				mm	INCH	DRAWN BY MLONG	DATE 2004/03/25	TITLE DDR2 DIMM, 1.00MM PITCH 240 CKTS, 25 DEG.				
			4 PLACES	± ---	± ---	CHECKED BY SRAMESH	DATE 2004/03/26					
			3 PLACES	± ---	± ---	APPROVED BY GGLEE		DATE 2004/03/26	MOLEX INCORPORATED			
			2 PLACES	± 0.25	± ---							
			1 PLACE	± ---	± ---	ANGULAR ± 5 °		DOCUMENT NO. SD-87803-010		SHEET NO. 1 OF 5		
REV	B1	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			MATERIAL NO. SEE TABLE							
					SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

10 9 8 7 6 5 4 3 2 1

F

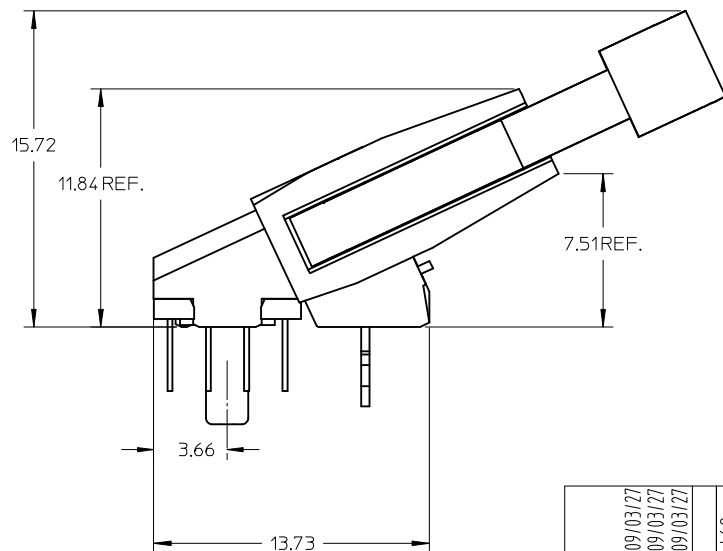
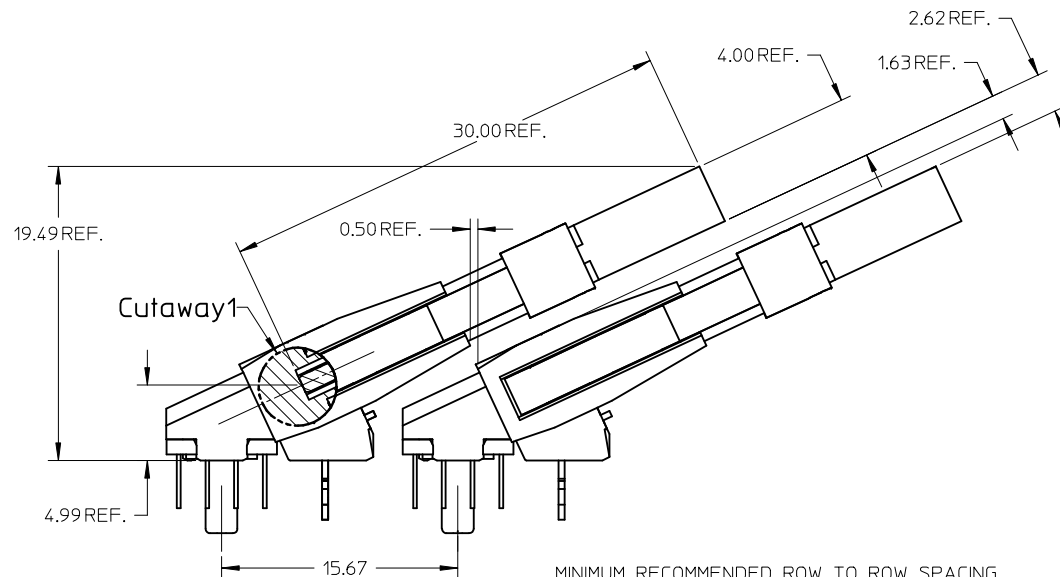
E

D

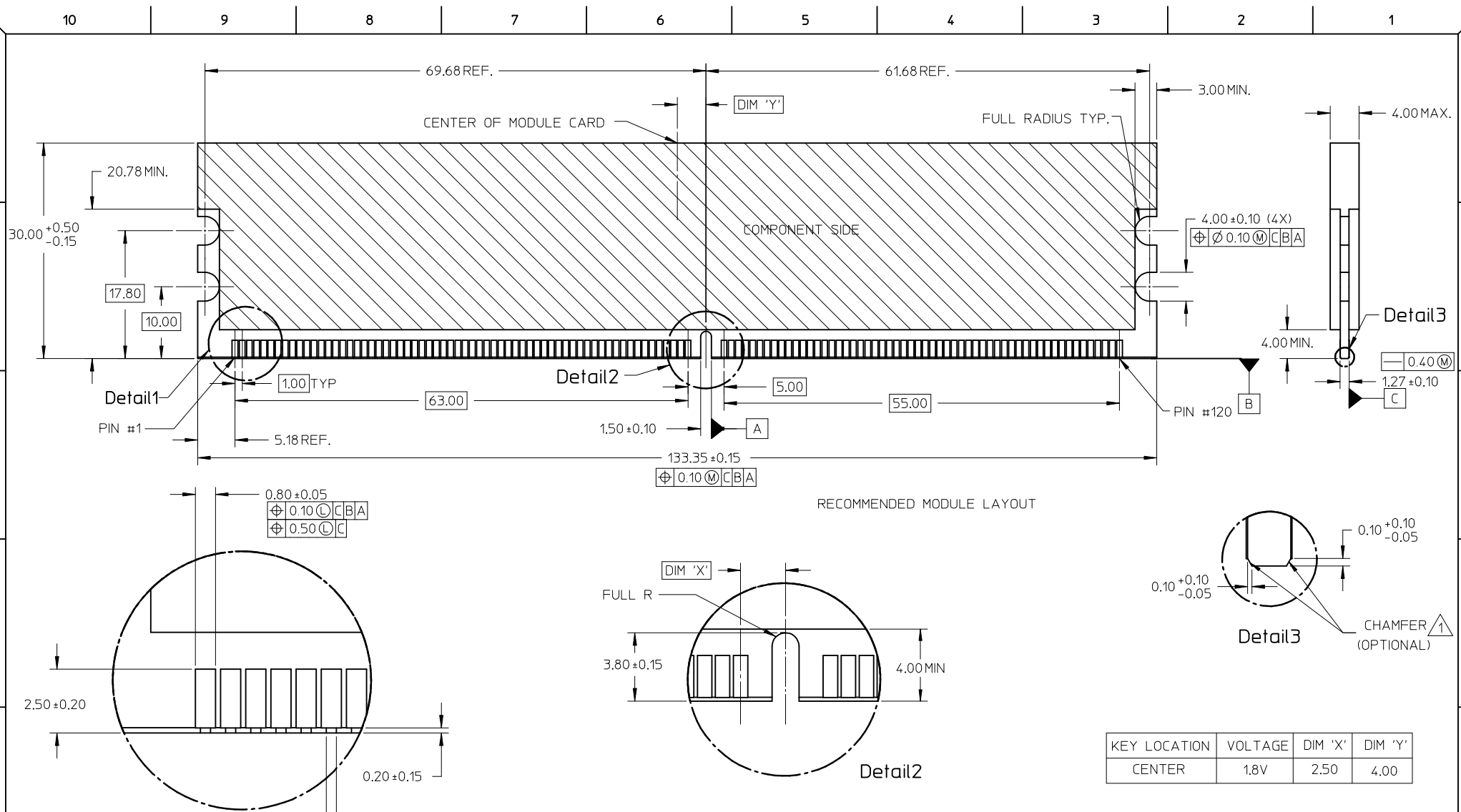
C

B

A



ADDED OPTION EC NO: S2009-0629 DRWN: CCTEH 2009/03/27 CHKD: CGTAN 2009/03/27 APPR: SHLENI 2009/03/27 REV	DESCRIPTION	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
				mm	INCH	DRAWN BY MLONG	DATE 2004/03/25	TITLE DDR2 DIMM, 1.00MM PITCH 240 CKTS, 25 DEG.			
			4 PLACES	± ---	± ---	CHECKED BY SRRAMESH	DATE 2004/03/26				
			3 PLACES	± ---	± ---	APPROVED BY GGLEE	DATE 2004/03/26	MOLEX INCORPORATED			
			2 PLACES	± 0.25	± ---	MATERIAL NO.	DOCUMENT NO.				
			1 PLACE	± ---	± ---	SEE TABLE		SD-87803-010			
			ANGULAR ± 5 °			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



RECOMMENDED MODULE LAYOUT

KEY LOCATION	VOLTAGE	DIM 'X'	DIM 'Y'
CENTER	1.8V	2.50	4.00

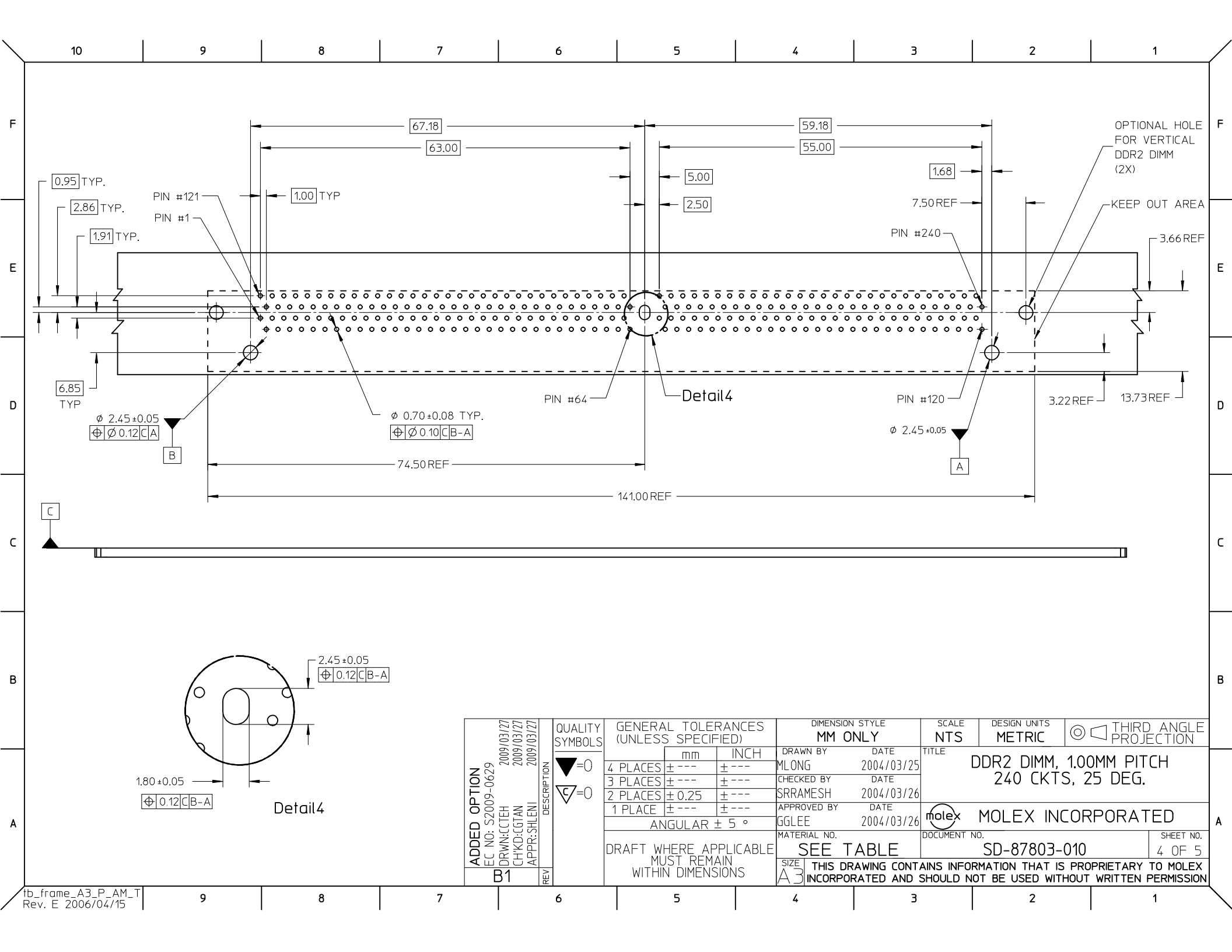
Detail1

Detail2

Detail3

NOTES:
1. MODULE CARD USED IN PRODUCT TESTING ARE CHAMFERED.

ADDED OPTION EC NO: S2009-0629 DRWN:CTEH 2009/03/27 CHKD:CGAN 2009/03/27 APPR:SHENI 2009/03/27	DESCRIPTION	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION
			4 PLACES 3 PLACES 2 PLACES 1 PLACE	mm	INCH	DRAWN BY MLONG	DATE 2004/03/25	TITLE DDR2 DIMM, 1.00MM PITCH 240 CKTS, 25 DEG.		
				± ---	± ---	CHECKED BY SRRAMESH	DATE 2004/03/26			
				± 0.25	± ---	APPROVED BY GGLEE	DATE 2004/03/26			
				± ---	± ---	MOLEX MOLEX INCORPORATED				
ANGULAR ± 5 °			MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-87803-010		SHEET NO. 3 OF 5			
B1	REV		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				



F

E

D

C

B

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F

E

D

C

B

A

PART NO.	VOLTAGE KEY	DIM 'P'	DIM 'Q'	RECOMMENDED PCB THICKNESS	CONTACT AREA PLATING	SOLDERTAIL PLATING	LUBRICATION			
87803-0002	1.8V	2.79	3.18	1.57	0.38µM/ 15µ" GOLD OVER 1.27µM/ 50µ" MIN NICKEL	2.54µM/ 100µ" MIN. TIN (MATTE) OVER 1.27µM/ 50µ" MIN NICKEL	NO			
87803-0022							YES			
87803-0012		3.18	4.83	2.36			NO			
87803-0032							YES			
87803-0052		4.00		3.18			NO			
87803-0062							YES			
87803-0102		2.79	3.18	1.57	0.76µM/ 30µ" GOLD OVER 1.27µM/ 50µ" MIN NICKEL		NO			
87803-0122							YES			
87803-0112		3.18	4.83	2.36			NO			
87803-0132							YES			
87803-0152		4.00		3.18			NO			
87803-0162							YES			

ADDED OPTION

EC NO: S2009-0629

DRWN: CTEH

CHKD: GTAN

APPR: SILENI

B1

2009/03/27

2009/03/27

2009/03/27

DESCRIPTION

REV

QUALITY SYMBOLS

▽=0

▽=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

mm

INCH

4 PLACES

± ---

± ---

3 PLACES

± ---

± ---

2 PLACES

± 0.25

± ---

1 PLACE

± ---

± ---

ANGULAR ± 5 °

DRAFT WHERE APPLICABLE
MUST REMAIN
WITHIN DIMENSIONS

DIMENSION STYLE

MM ONLY

DRAWN BY

MLONG

DATE

2004/03/25

CHECKED BY

SRRAMESH

DATE

2004/03/26

APPROVED BY

GGLEE

DATE

2004/03/26

MATERIAL NO.

SEE TABLE

SIZE

A3

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

SCALE

NTS

DESIGN UNITS

METRIC

THIRD ANGLE PROJECTION

TITLE

DDR2 DIMM, 1.00MM PITCH
240 CKTS, 25 DEG.

moLEX

MOLEX INCORPORATED

DOCUMENT NO.

SD-87803-010

SHEET NO.

5 OF 5